

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
G. GLENN HENRY	07/06/2016
TERRY PARKS	07/06/2016
RECEIVING PARTY DATA	
Name:	VIA ALLIANCE SEMICONDUCTOR CO., LTD.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15090708
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ATTORNEY DOCKET NUMBER:	VAS.3062
NAME OF SUBMITTER:	TAYSIE J. LOCKE
SIGNATURE:	/Taysie J. Locke/
DATE SIGNED:	08/01/2016
Total Attachments: 1	
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Docket: VAS.3062

Assignment

ASSIGNMENT

TITLE OF INVENTION	DIRECT EXECUTION BY AN EXECUTION UNIT OF A MICRO-OPERATION LOADED INTO AN ARCHITECTURAL REGISTER FILE BY AN ARCHITECTURAL INSTRUCTION OF A PROCESSOR
DOCKET NUMBER	VAS.3062

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on even date herewith;

AND WHEREAS, VIA Alliance Semiconductor Co., Ltd. together with any successors, legal representatives, or assigns thereof, with its principal office at Room 301, No.2537, Jinke Road, Zhangjiang Hi-Tech Park, Shanghai 201203, CN, wants to acquire the entire right, title and interest in and to the said invention(s), and to the said application and any Letters Patent that may issue thereon;



NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledge, I have sold, assigned, transferred and set over, and do hereby sell, assign, transfer and set over to the said VIA Alliance Semiconductor Co., Ltd., its successors and assigns, the entire right, title and interest in and to the said invention and in and to the said application and all patents which may be granted thereon, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I/we hereby authorize and request the Commissioner of Patents, and any officials of foreign countries whose duty it is to issue patents on applications, to issue all patents for said invention, or patents resulting therefrom, insofar as my interest in concerned, to the said VIA Alliance Semiconductor Co., Ltd. as assignee of my entire right, title and interest;

I ALSO HEREBY sell and assign to VIA Alliance Semiconductor Co., Ltd., its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights;

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant that I will communicate to said VIA Alliance Semiconductor Co., Ltd., or to its successors, assigns and legal representatives, any facts known to me respecting said invention, and at the expense of said VIA Alliance Semiconductor Co., Ltd., testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said VIA Alliance Semiconductor Co., Ltd., its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand this day and year:

INVENTOR NAME(S)	RESIDENCE AND MAILING ADDRESS	CITIZENSHIP	SIGNATURE	DATE
G. Glenn Henry	411 Lake Cliff Trail Austin, TX 78746	US		7/6/16
Terry Parks	#6 Carriage House Lane Austin, TX 78737	US		7/6/16